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MICROELECTRONIC ADHESIVES (*ELECTRICALLY NON CONDUCTIVE*)

DIE ATTACH ■ SUBSTRATE ATTACH ■ HEAT SINK ■ LEAD SEALING

FEATURES	APPLICATIONS	Product	Shelf Life	Pot Life	Sp. Gravity	Viscosity @ 25°C (cps)	Cure Schedule	Coefficient of Thermal Expansion (10 ⁻⁶ /°C)		Tg (°C)	Operating Temp. Range	Thermal Conductivity (W/m ² K)	Volume Resistivity (Ohm-cm)
								-40°C to 25°C	25°C to 120°C				
➤ Low thermal expansion ➤ Good moisture resistance ➤ Excellent thermal cycle performance ➤ One and two components ➤ Very good adhesion	➤ Substrate Attach ➤ Lid Seal ➤ SMD Attach ➤ Stacking component ➤ Die Attach applications - o Chip-On-Board - o LED - o TCP - o MCM-L,C, & D	EB-316TM	1 year @ 25°C	45 Min @25°C	1.35	Paste	1 hrs @ 160°C	77	-	109	-55°C to 150°C	0.5	3x10 ¹³
		EB-315	1 year @ 25°C	90 Min @25°C	1.8	Paste	1 hrs @ 175°C	25	40	182	-55°C to 230°C	0.7	2x10 ¹⁵
		EB-350-3T	4 months @ 25°C	20 Min @80°C	1.5	Non-Sag Paste	1 hrs @ 150°C	32	41	120	-55°C to 150°C	1.0	1x10 ¹⁵
		EB-402-1	1 year @ -40°C	12 Min @ 125°C	2.14	>250,000	2 hrs @ 125°C	24	33	145	-55°C to 150°C	1.8	2x10 ¹⁵
		EB-403-1	1 year @ -40°C	30 Min @80°C	2.1	Non-Sag Paste	1/2 hr @ 150°C	28	38	145	-55°C to 150°C	1.75	6x10 ¹⁵
		EB-404-1	4 months @ 25°C	10 Min @80°C	1.6	40,000	1/2 hr @ 150°C	39	51	130	-55°C to 150°C	1.2	3x10 ¹⁵
		EB-414-1	1 year @ -40°C	12 Min @ 125°C	2.1	20,000	1/2 hr @ 150°C	35	48	124	-55°C to 150°C	1.6	2x10 ¹⁵
		EB-407	1 year @ 25°C	2 hrs @ 25°C	2.3	Paste	1/2 hrs @ 100°C	27	60	77	-40°C to 120°C	1.3	7x10 ¹⁵
		EB-425	1 year @ 25°C	>4 hrs @ 25°C	2.3	>250,000	2 hrs @ 100°C + 2 hrs @ 150°C	29	39	165	-55°C to 200°C	1.7	1x10 ¹⁶
		EB-415-1	1 year @ -40°C	12 Min @125°C	2.2	>250,000	1/2 hr @ 160°C	24	35	142	-55°C to 150°C	1.9	2x10 ¹⁵

DISCLAIMER: All data given here is offered as a guide to the use of these materials and not as a guarantee of their performance. The user should evaluate their suitability for own purposes. Properties are typical and should not be used in preparing specifications. Statements are not to be construed as recommendations to infringe any patent.